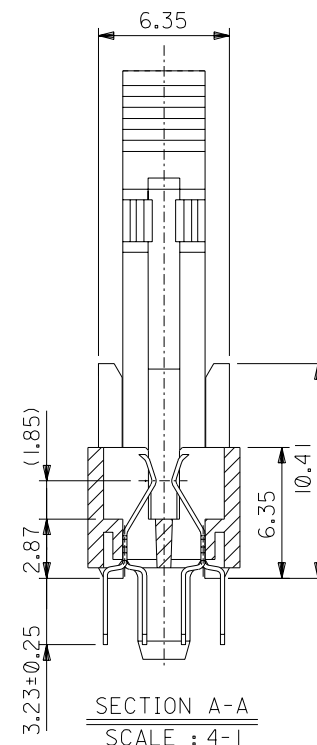
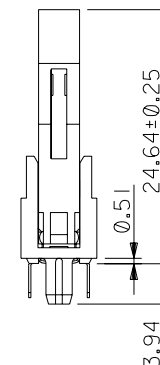
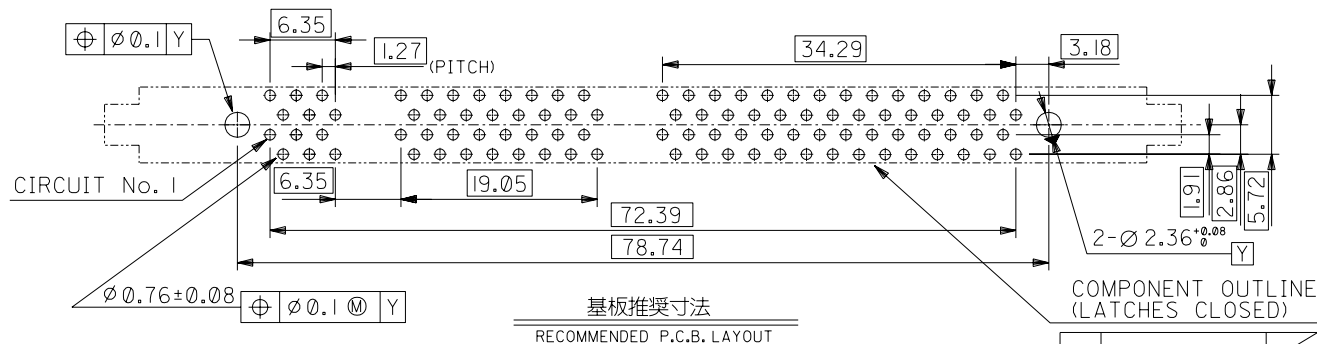
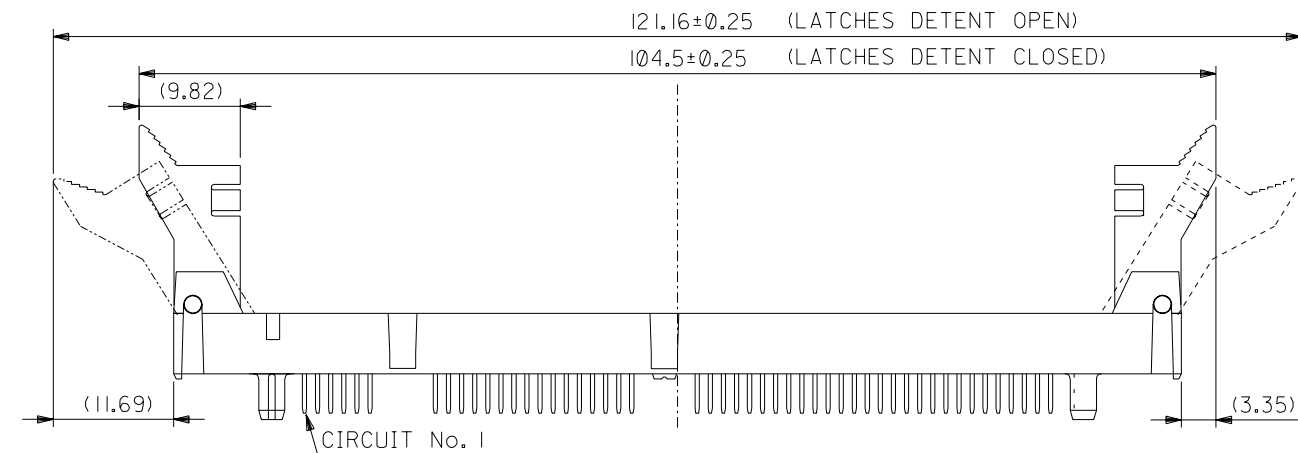
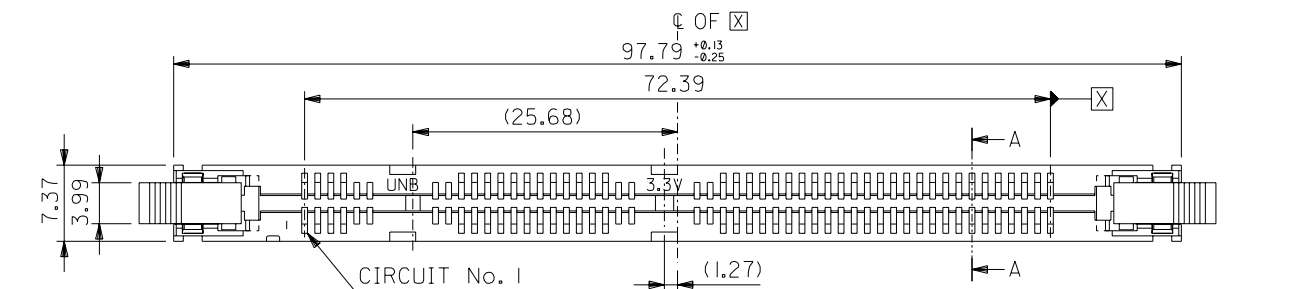




角度 ANGLE	$\pm 30^\circ$						
30 以上 OVER	± 0.3						
10 以上 OVER 30 UNDER	± 0.25	A	変更 REVISD (J2004-4509)	Y.W.	M.S.	04/05/31	
10 未満 UNDER	± 0.2	0	新規作成 PROPOSED (JD90709)	Y.H.	M.S.	98/11/12	
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	APP'D BY	尺度 SCALE 2 - 1

材料 MATERIAL	注参照 SEE NOTES
仕上げ FINISH	注参照 SEE NOTES
適用電線範囲 WIRE RANGE	— # —
被覆外径 INS. RANGE	— # —
DRAWN BY '98/11/12	CHK'D BY '98/11/12
T. Kiyota	H. Saito
APP'D BY	尺度 SCALE 2 - 1

MOLLEX MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称 1.27 PITCH DIMM 100 CIRCUIT MULTI-KEY HOUSING ASS'Y -LEAD FREE-	
DWG. NO. SD-71251-5101	SHEET 1 OF 2 REV A

注記
NOTES:

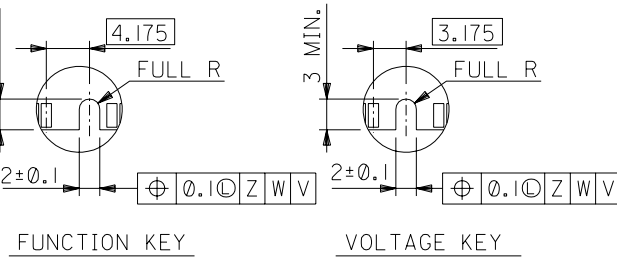
7. 製造日コードはハウジングの側面に刻印されます。
PRODUCT WILL HAVE DATE CODE
STAMPED ON SIDE OF HOUSING.
8. 材質
ハウジング：耐熱性樹脂（黒色）
ラッチ：耐熱性樹脂（アイボリー）
ターミナル：リン青銅
- MATERIALS:
HOUSING- HIGH-TEMP THERMOPLASTIC
COLOR: BLACK
LATCHES - HIGH-TEMP THERMOPLASTIC
COLOR: IVORY
TERMINAL- PHOSPHOR BRONZE
9. メッキ仕様
接点部：金メッキ 0.05-0.25MICROMETER
パラジウムニッケル下地 0.76MICROMETER MIN.
半田付け部：錫メッキ 3.81MICROMETER MIN.
下地メッキ：ニッケルメッキ 1.27MICROMETER MIN.
PLATING:
CONTACT AREA: GOLD 0.05-0.25MICROMETER
OVER PALLADIUM-NICKEL

SOLDER TAILS: TIN
3.8 MICROMETER MIN.
UNDERPLATE: NICKEL 1.27 MICROMETER MIN.

⑩ モジュール基板の真直度は、底辺より4mmの範囲に適用。
STRAIGHTNESS OF MODULE APPLIES TO
THE AREA FROM THE BOTTOM OF THE
CARD UP 4.

11. 電解メッキなどのために、パッドにタブを設ける場合は、それがコネクタのコンタクト部を損傷する原因とならないよう、ご配慮下さい。

IF TIE BARS ARE ATTACHED TO PADS,
THE TIE BAR SHOULD BE ON AN INTERNAL
LAYER, SO THAT THE REMNANT CANNOT
CAUSE DAMAGE TO THE CONTACTS.



基板推奨寸法

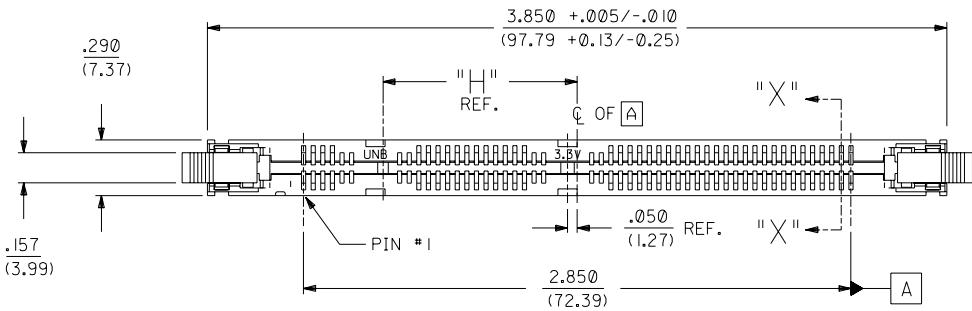
RECOMMENDED P.C.B. LAYOUT

[illegible]

材料 MATERIAL	注参照 SEE NOTES	 MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH	注参照 SEE NOTES	REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE	— # —	TITLE 名称 1.27 PITCH DIMM 100 CIRCUIT MULTI-KEY HOUSING ASS'Y -LEAD FREE-	
被覆外径 INS. RANGE	— # —		
DRAWN BY '98/11/12 T. Kikuta	CHK'D BY H. Sato	DWG. NO. SHEET 2 OF 2 REV	
APP'D BY S. (Manager)	尺度 SCALE 2 - 1	SD-71251-5101 A	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX(JAPAN) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION
本図面は日本モレックス(株)の所有する情報を含むもので当社の許可なく複製を禁止する。 FN-01C(D)

EN-0 IC(032)MXJ-32



NOTES:

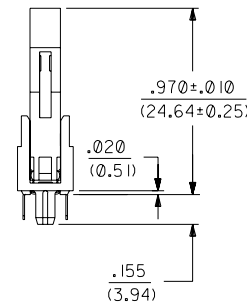
1. CARD SLOT ACCEPTS .050±.004 (1.27±0.10) MODULE THICKNESS. (MEASURED OVER P.C. PADS).
2. ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.
3. REFER TO PRODUCT SPEC. PS-71243 FOR PERFORMANCE SPECIFICATIONS.
4. PRODUCT IS PACKAGED IN TRAYS.
5. RECOMMENDED MODULE LAYOUT SHALL BE PER MO-I61.
6. RECOMMENDED PLATING ON MODULE PADS: 30 MICROINCH/(0.76 MICROMETER) MINIMUM HARD GOLD (Au) OVER 79 MICROINCH/(2.0 MICROMETER) MINIMUM NICKEL (Ni).
7. PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

MATERIALS:

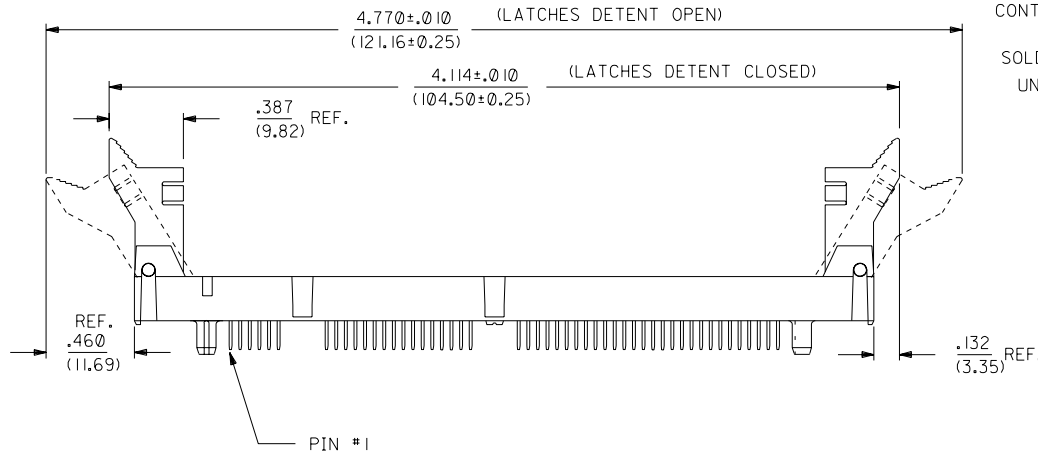
HOUSING - GLASS FILLED LIQUID CRYSTAL POLYMER (LCP), UL 94V-0, COLOR: BLACK.
 TERMINAL - PHOSPHOR BRONZE
 LATCHES - GLASS FILLED HIGH TEMPERATURE NYLON, UL 94V-0, COLOR: IVORY.

PLATING:

CONTACT AREA: MOLEX EBI LUBRICANT OVER
 GOLD (Au): THICKNESS=10 MICROINCH/(0.25 MICROMETER) MINIMUM.
 SOLDER TAILS: TIN (Sn): THICKNESS=150 MICROINCH/(3.81 MICROMETER) MINIMUM.
 UNDERPLATE: NICKEL (Ni) OVER ENTIRE CONTACT.



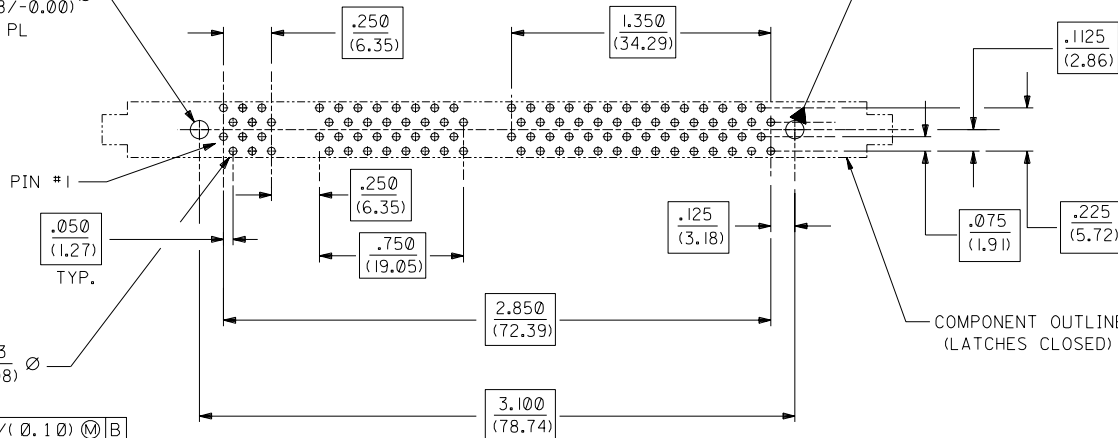
NOTE FOR LEAD FREE CONVERSION:
 THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.



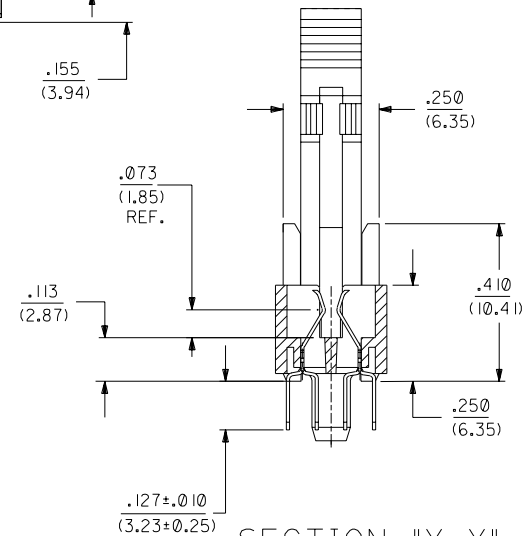
71251-5101 SHOWN

⌀ .004/(0.10) B 2 PL

.093 +.003/-0.000
 (2.36 +0.08/-0.00) Ø
 2 PL



RECOMMENDED
 P.C. BOARD HOLE PATTERN
 (CONNECTOR SIDE)



SECTION "X-X"

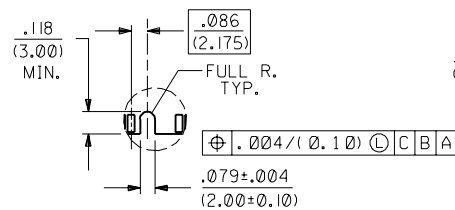
SCALE 4:1

C1	ADD LEAD FREE NOTE ECN# UCP2004-1732 DMORGAN 04/03/09
C	CHANGE PLATING ECN# UDT2002-0712 DMORGAN 02/01/22
B	CHG Sn-Pb THICKNESS ECN# UDT1999-0454 DMORGAN 99/08/09
A1	REVISED PER ECR# U80435 97-8-8 LAURX
A	REVISED PER ECR# U70042 96-7-23 LAURX
2	REVISED PER ECR# U61257 4-10-96 JCL
	X-RELEASE PER ECR# U61175 3-26-96 JCL

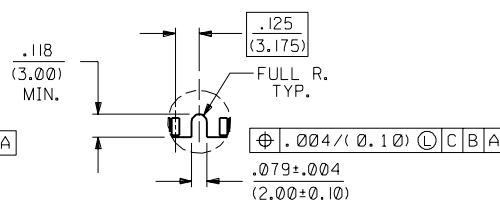
DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		TITLE 71251-5101		REVISE ONLY ON CAD SYSTEM	
3 PLACE ± .005	INCH	2	A1	1	C1
2 PLACE ± --- ± 0.13	METRIC	1	C1	1	C1
1 PLACE --- ± 0.25		MFG, SH.	REV.	LTR.	REVISIONS
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		PART NO. MOLEX INCORPORATED LITSE,ILL. 60532		SHEET NO. 1 OF 2	
DRWG. BY JCL	CHK'D. BY DCB	FILE NAME ST125151 DCN	DATE 03/26/96	DIV. SIZE CP C	
APPR'D. BY DCB	SCALE 2: 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DRAWG. NO. SDA-71251-5***	

13		12		11		10		9		8		7		6		71251		4		3		2		1	
PART NUMBER		DESCRIPTION		FUNCTION KEY		VOLTAGE KEY		DIM. "H"																	
71251-5101		3.3 VOLT UNBUFFERED		OFFSET RIGHT		CENTER		1.011 (25.68)																	
71251-5102		5.0 VOLT UNBUFFERED		OFFSET RIGHT		OFFSET LEFT		1.011 (25.68)																	

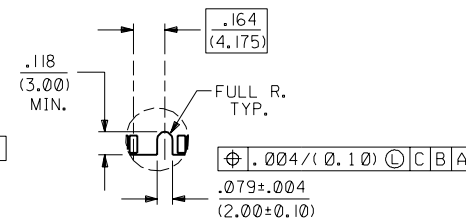
- NOTES:
1. STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP .157/(4.00).
 2. IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.



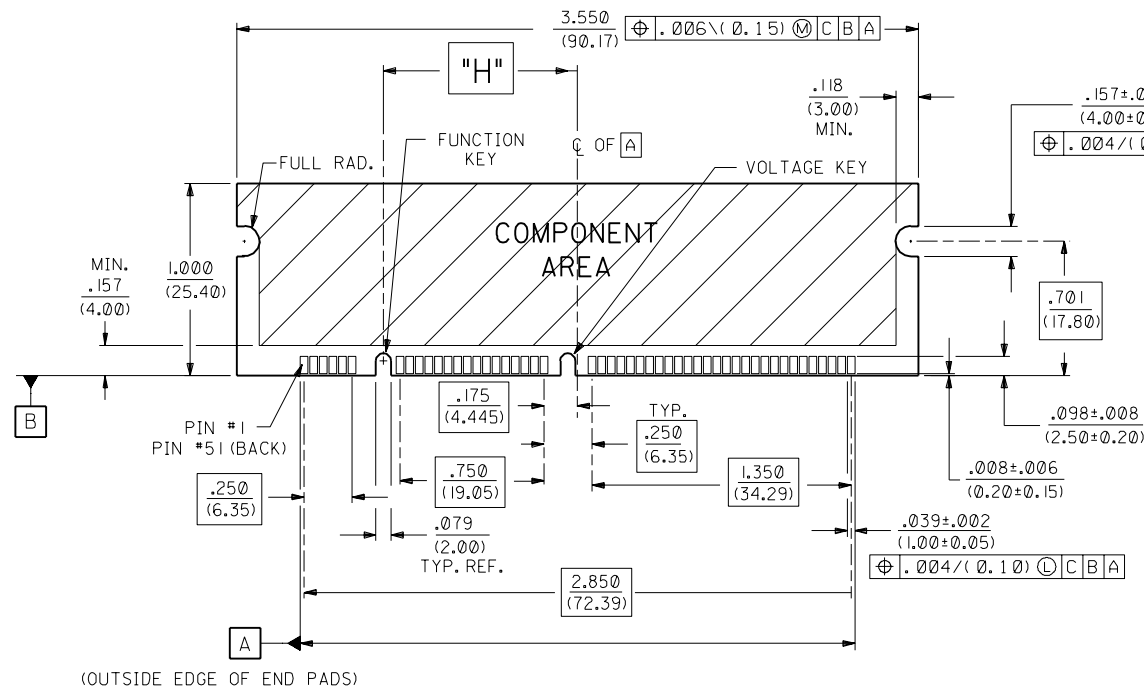
OFFSET LEFT KEY



CENTERED KEY



OFFSET RIGHT KEY



RECOMMENDED MODULE LAYOUT
100 CKT 3.3V UNBUFFERED

DIMENSIONS SHOWN (METRIC) INCH		TITLE	
UNLESS OTHERWISE SPECIFIED TOLERANCES ANGULAR ± 1/2°		.050 PITCH DIMM 100 CKT MULTI-KEY SALES DRAWING	
3 PLACE ± .005	INCH METRIC	MOLEX INCORPORATED	
2 PLACE ± .01	± 0.13	U.S.A.	
1 PLACE --- ± 0.25		DATE 03/26/96	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		PART NO. SDA-71251-5	
DRAWN BY JCL		REV. 1	
CHK'D BY DCB		LTR. 1	
APP'D BY DCB		REV. 1	
SCALE 2: 1		REV. 1	
FILE NAME 5725152		DIV. CP	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		REVISE ONLY ON CAD SYSTEM	